

# MA4X174 (MA174)

## Silicon planar type

For small power rectification and surge absorption

### ■ Features

- Two isolated elements contained in one package, allowing high-density mounting
- High breakdown voltage:  $V_R = 200$  V

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	200	V
Repetitive peak reverse voltage		$V_{RRM}$	250	V
Non-repetitive peak reverse surge voltage		$V_{RSM}$	300	V
Output current	Single	$I_O$	100	mA
	Double		75	
Repetitive peak forward current	Single	$I_{FRM}$	225	mA
	Double		170	
Non-repetitive peak forward surge current *	Single	$I_{FSM}$	500	mA
	Double		375	
Junction temperature		$T_j$	125	$^\circ\text{C}$
Storage temperature		$T_{stg}$	-55 to +125	$^\circ\text{C}$

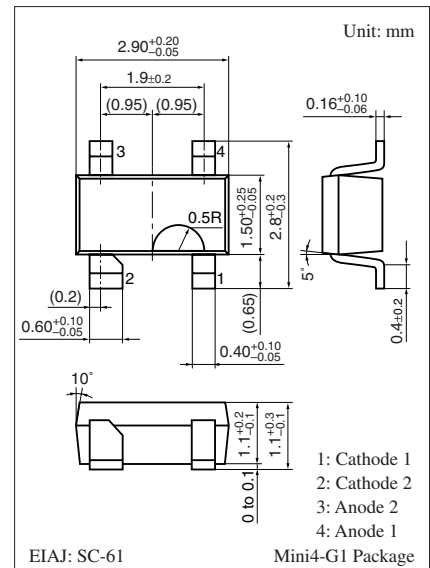
Note) \*:  $t = 1$  s

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100$ mA			1.3	V
Reverse current	$I_R$	$V_R = 200$ V			1.0	$\mu\text{A}$

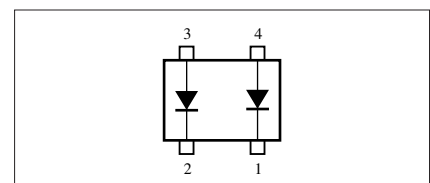
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 3 MHz.

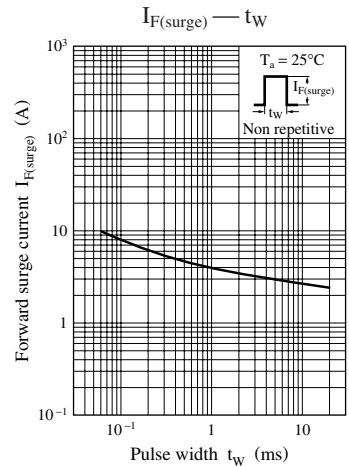
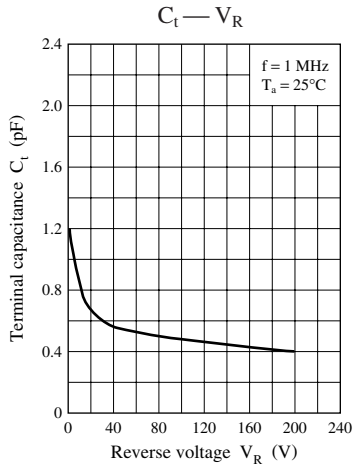
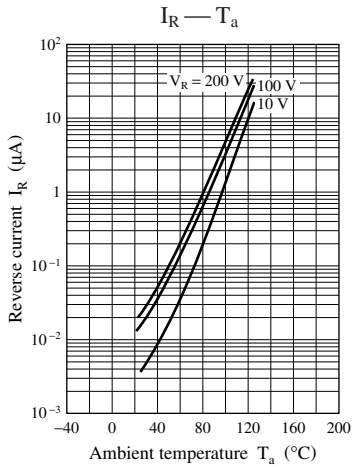
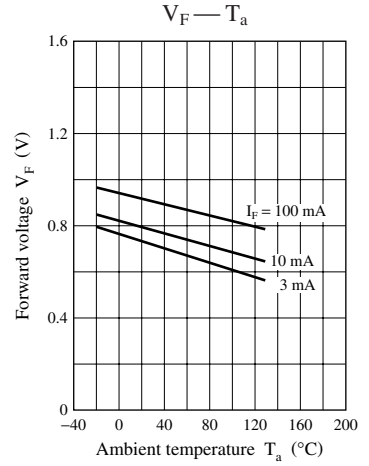
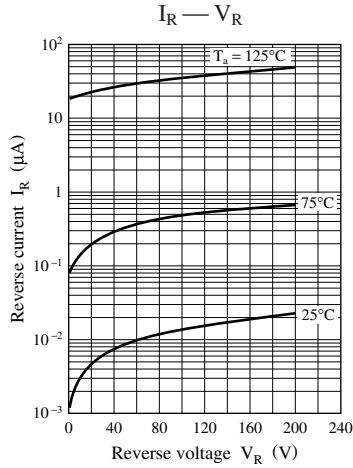
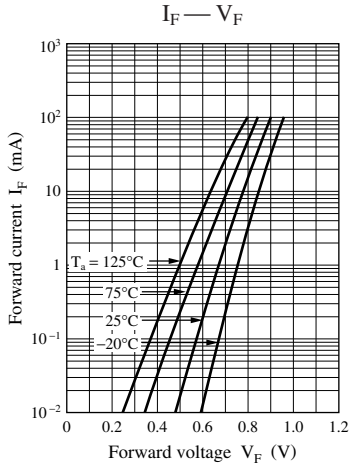


Marking Symbol: M2O

Internal Connection



Note) The part number in the parenthesis shows conventional part number.



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